

Thank You for Your Support

We would like to thank all investors who applied for the T2023-S\$ Temasek Bond.

We have been issuing Temasek Bonds since 2005, and are pleased that a Temasek Bond is open to retail investors in Singapore for the first time.

We welcome our new bondholders, especially our retail investors.

You join the investors of our other Temasek Bonds, as stakeholders with an interest in our performance as an investor, institution and steward.

TEMASEK BOND

5-year T2023-S\$ bond
Fixed interest rate
2.70% p.a.



To find out more, please visit
temasek.com.sg/bond

Introduction

Temasek Financial (IV) Private Limited is the issuer of the T2023-S\$ Temasek Bond, initially comprising:

- a Placement of S\$200 million to institutional, accredited and other specified investors;
- a Public Offer of up to S\$200 million to retail investors in Singapore.

Temasek fully guarantees all interest payments of the T2023-S\$ Temasek Bond and full repayment of the principal amount at maturity.

Bids from institutional, accredited and other specified investors in a book building process were used to determine the interest rate for the T2023-S\$ Temasek Bond.

The same interest rate was offered to retail investors in the Public Offer.

Allocation of the T2023-S\$ Temasek Bond

In view of the strong demand from retail investors, the Issuer and Temasek have decided to increase the issue size by S\$100 million for the Public Offer. The total issue size of S\$500 million is allocated as shown below:

Placement to institutional, accredited and other specified investors

Total size	: S\$200 million
Bids received	: about S\$1,438 million
Subscription rate	: just over 7 times

Public Offer to retail investors in Singapore

Total size	: S\$300 million
Valid applications received	: about S\$1,676 million
Subscription rate	: about 5 times

Successful applicants in the Public Offer will have their T2023-S\$ Temasek Bond allocations credited to their respective CDP accounts on 25 October 2018.

Applicants who did not receive their full allocations will have their respective balances refunded starting from 24 October 2018, into their designated bank account or CPF Ordinary Account, depending on their initial source of application funds.

Key Dates

Wed 24 Oct 2018	For applicants who did not receive their full allocations, refunds to their bank accounts or CPF Ordinary Account will begin, in full or in part as appropriate.
Thu 25 Oct 2018	Issue date.
Thu 25 Oct 2018	Retail investors can check their allocations in their CDP accounts.
Fri 26 Oct 2018	Expected start of trading on the Main Board of SGX-ST at 9:00 am. The Trading Name for the bonds will be Temasek 2.7% 231025XB# and the SGX-ST stock code will be TEKB .
Thu 25 Apr 2019	First interest payment. All payments will be made on or around 25 Apr and 25 Oct each year, until maturity in Oct 2023.

All applicants who submitted valid applications under the Public Offer of S\$300 million have been allocated all or a proportion of the bonds they applied for, as follows:

Amount of Public Offer bonds applied for (S\$)	Public Offer bonds allocated per successful applicant (S\$)	Percentage allocated under the Public Offer (%)	Number of successful Public Offer applicants
1,000	1,000	0.3	1,009
2,000	2,000	1.1	1,711
3,000	3,000	1.3	1,326
4,000	4,000	0.7	555
5,000	5,000	9.1	5,441
6,000	6,000	1.3	641
7,000 to 30,000	6,000	56.6	28,295
31,000 to 100,000	6,000	24.6	12,319
101,000 to 200,000	7,000	3.4	1,436
201,000 to 335,000	8,000	1.0	357
336,000 to 3,001,000	9,000	0.6	192
Total		100	53,282

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